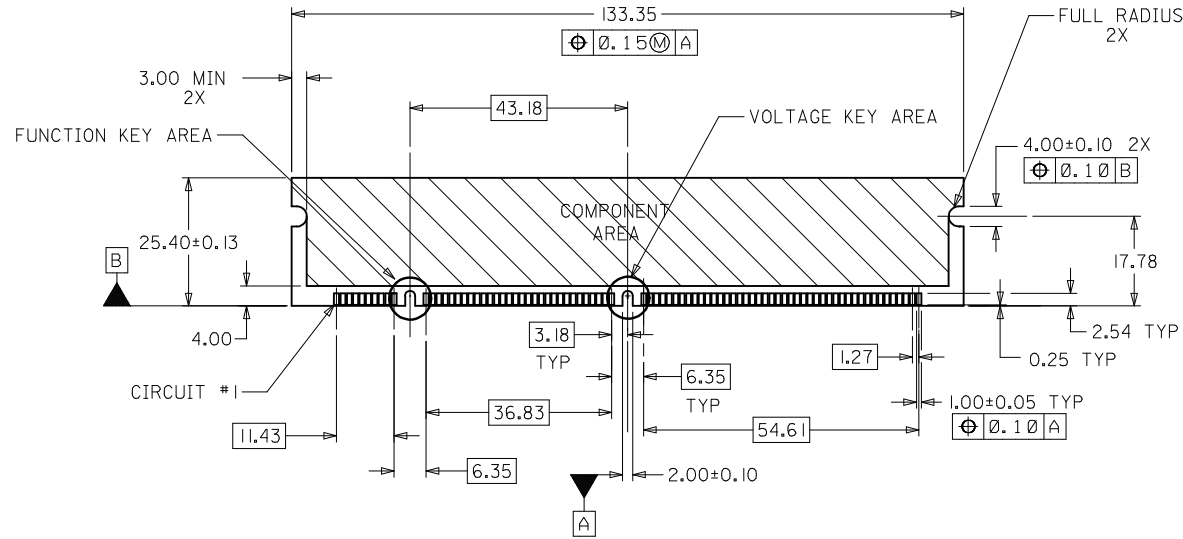


NOTES:

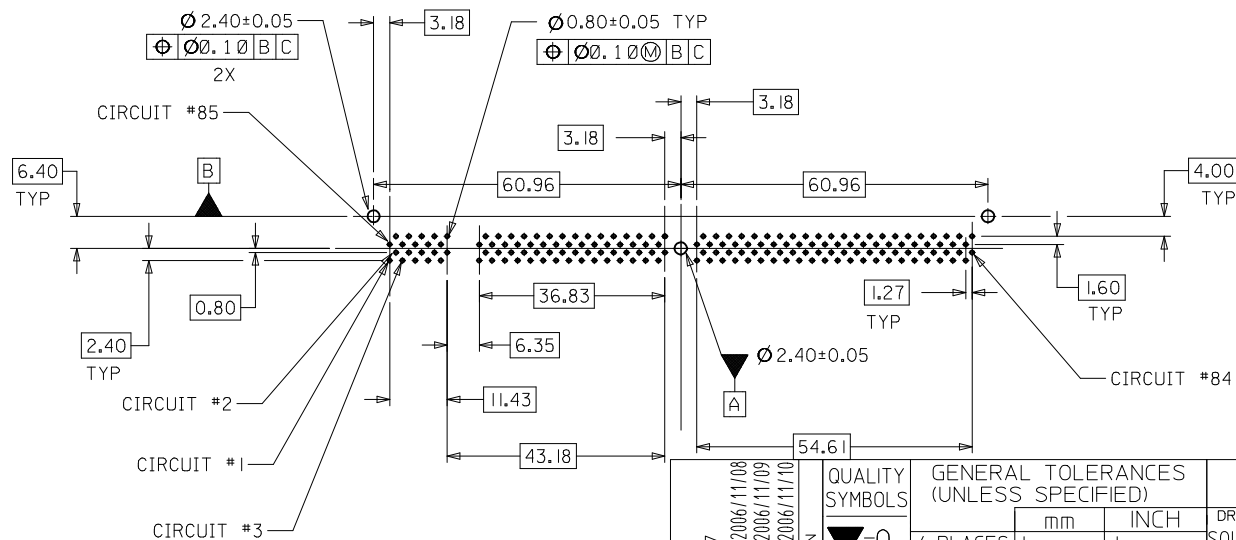
1. PRODUCT SPEC PS-87609-002 APPLIES.
2. PRODUCT IS PACKAGED IN TRAYS.
3. MATERIALS:
 HOUSING, COVER & BASEPLATE - LCP, GLASS FILLED, UL 94V-0, COLOR: BLACK
 TERMINAL - PHOSPHOR BRONZE
 LATCHES - HIGH-TEMP NYLON, GLASS FILLED, UL 94V-0, COLOR: BEIGE
 FORCKLOCKS - COPPER ALLOY OR STEEL ALLOY

4. PLATING:
 CONTACT AREA:
 SEE TABLE ON SHEET 3 OF 3
 FOR GOLD PLATING OPTION AT CONTACT AREA
 SOLDER TAIL: 75µN/(1.91µM) MIN. TIN
 UNDERPLATE: 50µN/(1.27µM) MIN. NICKEL

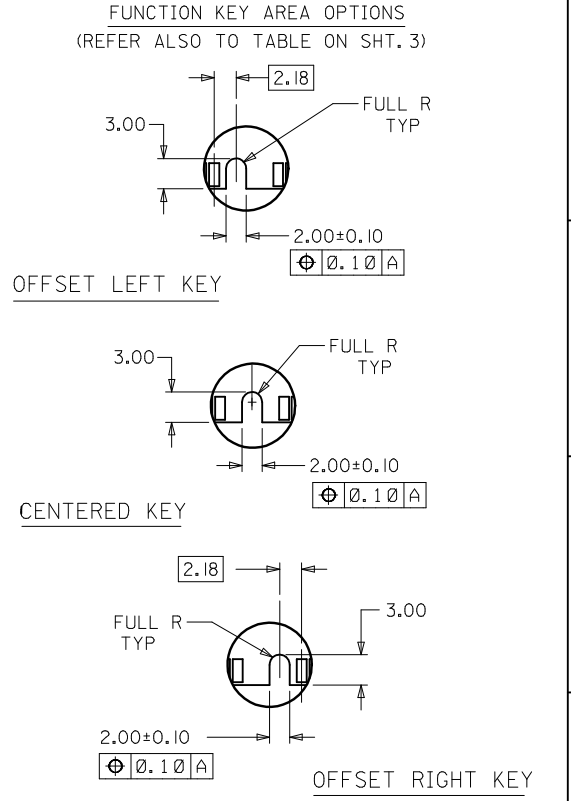
VOID P/N EC NO: S2007-0207 DRWN:SKANG 2006/11/08 CHKD:MLONG 2006/11/09 APPR:SKTOH 2006/11/10	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY SQUEK	DATE 2000/01/21	TITLE DDR DIMM, 127MM PITCH 168 CKTS, R/A			
		4 PLACES	± ---	± ---	CHECKED BY KCLING	DATE 2000/03/01	MOLEX INCORPORATED DOCUMENT NO. SD-87609-001 SHEET NO. 1 OF 3			
		3 PLACES	± ---	± ---	APPROVED BY SKTOH	DATE 2000/03/03				
	2 PLACES	± 0.25	± ---	MATERIAL NO. SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
	1 PLACE	± ---	± ---	ANGULAR ± 5 °						
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				SIZE A3						



RECOMMENDED MODULE LAYOUT
(PER JEDEC STANDARD MO-161, 168 CKT. 3.3V)

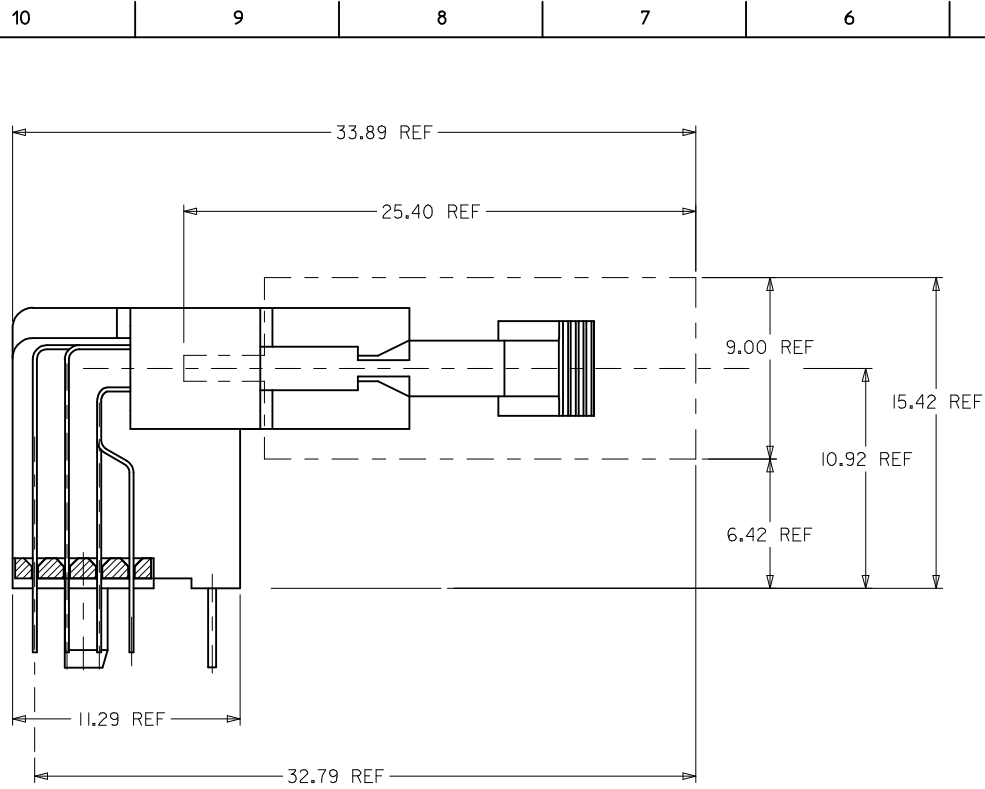


RECOMMENDED P.C. BOARD HOLE PATTERN
(CONNECTOR SIDE)

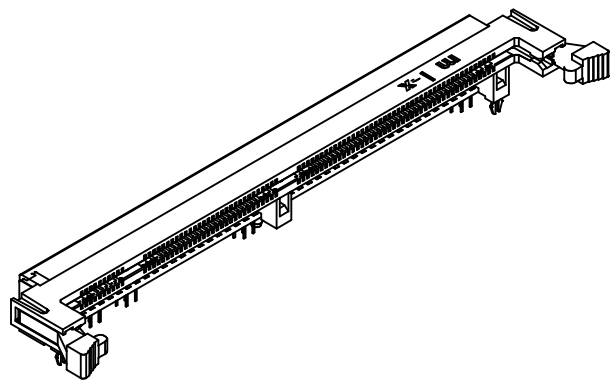


- NOTES:
1. STRAIGHTNESS OF MODULE APPLIES TO THE AREA FROM THE BOTTOM OF THE CARD UP 4.00(157)
 2. RECOMMENDED PLATING ON MODULE PADS: 0.76 MICROMETER(30 MICROINCH) MINIMUM HARD GOLD OVER 2.0 MICROMETER(79 MICROINCH) MINIMUM NICKEL.

VOID P/N EC NO: S2007-0207 DRWN:SKANG CHKD:MLONG APPR:SKTOH 2006/11/08 2006/11/09 2006/11/10	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± --- ANGULAR ± 5 °	DIMENSION STYLE MM ONLY DRAWN BY: SQUEK DATE: 2000/01/21 CHECKED BY: KCL ING DATE: 2000/03/01 APPROVED BY: SKTOH DATE: 2000/03/03	SCALE NTS TITLE DDR DIMM, 127MM PITCH 168 CKTS, R/A	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE	MATERIAL NO. SKTOH 2000/03/03	MOLEX INCORPORATED	SHEET NO. 2 OF 3	
			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
			SIZE A3				



ACTUAL MODULE HEIGHT AND CLEARANCE
WHEN USING A 9.00MM THICK BY 25.40MM HEIGHT
MODULE (TYPICAL SOJ PACKAGING).



PART NUMBER	FUNCTION KEY	GOLD PLATING OPTION AT CONTACT AREA	DATUM VOLTAGE KEY	TAIL LENGTH P±0.25	RECOMMENDED PCB THICKNESS
87609-0051	LEFT	15μN/(0.38μM) MIN.	CENTER (3.3V)	2.79	1.57
87609-0052	CENTRE				
87609-0053	RIGHT				
87609-0151	LEFT	30μN/(0.76μM) MIN.	CENTER (3.3V)	3.18	2.36
87609-0152	CENTRE				
87609-0153	RIGHT				
87609-0061	CENTRE	15μN/(0.38μM) MIN.	CENTER (3.3V)	3.56	2.79
87609-0062	RIGHT				
87609-0162	RIGHT	30μN/(0.76μM) MIN.			
87609-0069	LEFT	15μN/(0.38μM) MIN.	CENTER (3.3V)	3.56	2.79
87609-0070	CENTRE				
87609-0071	RIGHT				
87609-0171	RIGHT	30μN/(0.76μM) MIN.			

VOID P/N EC NO: S2007-0207 DRWN:SKANG 2006/11/08 CHKD:MLONG 2006/11/09 APPR:SKTOH 2006/11/10	QUALITY SYMBOLS 	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY	DATE	TITLE			
		4 PLACES	± ---	± ---	SQUEK	2000/01/21	DDR DIMM, 1.27MM PITCH			
		3 PLACES	± ---	± ---	CHECKED BY	DATE	168 CKTS, R/A			
	± 0.25	± ---	KCLING	2000/03/01	MOLEX INCORPORATED					
1 PLACE	± ---	± ---	APPROVED BY	DATE	DOCUMENT NO.					
	ANGULAR ± 5 °		SKTOH	2000/03/03	SD-87609-001					
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.		SHEET NO.					
			SEE TABLE		3 OF 3					
			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							